

IN THE SPECIFICATION

Please replace the Abstract of the Disclosure with the text enclosed herein below. Also attached is a marked-up version of the Abstract of the Disclosure amended herein pursuant to 37 C.F.R. § 1.121(c)(1)(ii).

ABSTRACT OF THE DISCLOSURE

ai One or more stabilizers are disposed on the surface of a semiconductor device component prior to bonding the same to a higher level substrate. Upon assembly of the semiconductor device component face down upon a higher level substrate and joining conductive structures between the contact pads of the semiconductor device component and corresponding contact pads of the higher level substrate, the stabilizers at least partially stabilize the semiconductor device component on the higher level substrate to maintain a substantially parallel relation therebetween. The stabilizers can also be positioned and configured to define a minimum, substantially uniform distance between the semiconductor device component and the higher level substrate. The stabilizers may be preformed structures or fabricated on the surface of the semiconductor device component, such as by way of a stereolithographic method.